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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









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## 74LVQ573

## Low Voltage Octal Latch with 3-STATE Outputs

### **General Description**

The LVQ573 is a high-speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable ( $\overline{\text{OE}}$ ) inputs. The LVQ573 is functionally identical to the LVQ373 but with inputs and outputs on opposite sides of the package.

#### **Features**

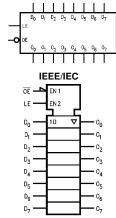
- Ideal for low power/low noise 3.3V applications
- Implements patented EMI reduction circuitry
- Available in SOIC JEDEC, SOIC EIAJ, and QSOP nackages
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Improved latch-up immunity
- $\blacksquare$  Guaranteed incident wave switching into 75 $\Omega$
- 4 kV minimum ESD immunity

#### **Ordering Code:**

Order Number	Package Number	Package Description
74LVQ573SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LVQ573SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVQ573QSC	MQA20	20-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150" Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

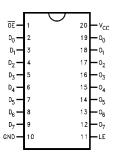
#### **Logic Symbols**



## **Pin Descriptions**

Pin Names	Description				
D <sub>0</sub> –D <sub>7</sub>	Data Inputs				
LE	Latch Enable Input				
ŌĒ	3-STATE Output Enable Input				
$O_0 - O_7$	3-STATE Latch Outputs				

## **Connection Diagram**



#### **Truth Table**

	Outputs		
ŌĒ	LE	D	O <sub>n</sub>
L	Н	Н	Н
L	Н	L	L
L	L	Х	$O_0$
Н	Χ	Х	Z

H = HIGH Voltage Z = High Impedance L = LOW Voltage X = Immaterial

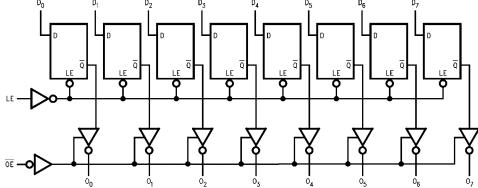
 $O_0$  = Previous  $O_0$  before HIGH-to-LOW transition of Latch Enable

## **Functional Description**

The LVQ573 contains eight D-type latches with 3-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the  $D_{\rm n}$  inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D-type input changes. When LE is LOW the latches store the information that was present on the

D-type inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE buffers are controlled by the Output Enable (OE) input. When OE is LOW, the buffers are enabled. When OE is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

## **Logic Diagram**



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

#### **Absolute Maximum Ratings**(Note 1)

Supply Voltage (V $_{CC}$ ) -0.5V to +7.0V

DC Input Diode Current  $(I_{IK})$ 

 $\begin{array}{c} \text{V}_{\text{I}} = -0.5 \text{V} & -20 \text{ mA} \\ \text{V}_{\text{I}} = \text{V}_{\text{CC}} + 0.5 \text{V} & +20 \text{ mA} \\ \text{DC Input Voltage (V}_{\text{I}}) & -0.5 \text{V to V}_{\text{CC}} + 0.5 \text{V} \end{array}$ 

DC Output Diode Current (I<sub>OK</sub>)

 $V_O = -0.5V \qquad \qquad -20 \text{ mA}$ 

 $V_{O} = V_{CC} + 0.5V$  +20 mA

DC Output Voltage (V<sub>O</sub>)  $-0.5V \text{ to V}_{CC} + 0.5V$ 

DC Output Source

or Sink Current ( $I_O$ )  $\pm 50 \text{ mA}$ 

DC V<sub>CC</sub> or Ground

Current ( $I_{CC}$  or  $I_{GND}$ )  $\pm 400 \text{ mA}$ 

Storage Temperature ( $T_{STG}$ )  $-65^{\circ}C$  to  $+150^{\circ}C$ 

DC Latch-Up Source or

Sink Current ±300 mA

# Recommended Operating Conditions (Note 2)

Supply Voltage (V<sub>CC</sub>) 2.0V to 3.6V

Operating Temperature (T<sub>A</sub>)  $-40^{\circ}\text{C}$  t Minimum Input Edge Rate ( $\Delta V/\Delta t$ )

V<sub>IN</sub> from 0.8V to 2.0V

V<sub>CC</sub> @ 3.0V 125 mV/ns

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions

for actual device operation.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

#### **DC Electrical Characteristics**

Symbol	Parameter	V <sub>CC</sub>	T <sub>A</sub> = +25°C		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	Units	Conditions
Symbol		(V)	Тур	Guaranteed Limits		Ullits	Conditions
V <sub>IH</sub>	Minimum High Level	3.0	1.5	2.0	2.0	V	V <sub>OUT</sub> = 0.1V
	Input Voltage	3.0	1.5	2.0	2.0	•	or V <sub>CC</sub> – 0.1V
V <sub>IL</sub>	Maximum Low Level	3.0	1.5	0.8	0.8	V	V <sub>OUT</sub> = 0.1V
	Input Voltage	0.0	1.0	0.0	0.6	•	or V <sub>CC</sub> – 0.1V
V <sub>OH</sub>	Minimum High Level	3.0	2.99	2.9	2.9	V	$I_{OUT} = -50 \mu A$
	Output Voltage	3.0		2.58	2.48	٧	$V_{IN} = V_{IL}$ or $V_{IH}$ (Note 3)
				2.00	2.40	-	$I_{OH} = -12 \text{ mA}$
V <sub>OL</sub>	Maximum Low Level	3.0	0.002	0.1	0.1	V	$I_{OUT} = 50 \mu A$
	Output Voltage	3.0		0.36	0.44	V	$V_{IN} = V_{IL}$ or $V_{IH}$ (Note 3)
		0.0		0.00	0.44	•	$I_{OL} = 12 \text{ mA}$
I <sub>IN</sub>	Maximum Input Leakage Current	3.6		±0.1	±1.0	μΑ	$V_I = V_{CC}$ , GND
I <sub>OLD</sub>	Minimum Dynamic	3.6			36	mA	$V_{OLD} = 0.8 V_{Max} \text{ (Note 5)}$
I <sub>OHD</sub>	Output Current (Note 4)	3.6			-25	mA	$V_{OHD} = 2.0V V_{Min} \text{ (Note 5)}$
Icc	Maximum Quiescent	3.6		4.0	40.0	μА	$V_{IN} = V_{CC}$
	Supply Current	3.0					or GND
loz	3-STATE						$V_{I}(\overline{OE}) = V_{IL}, V_{IH}$
	Leakage Current	3.6		±0.25	±2.5	μΑ	$V_I = V_{CC}$ , GND
							$V_O = V_{CC}$ , GND
V <sub>OLP</sub>	Quiet Output Maximum Dynamic V <sub>OI</sub>	3.3	0.4	0.8		٧	(Note 6)(Note 7)
V <sub>OLV</sub>	Quiet Output	3.3	-0.4	-0.8		٧	(Note 6)(Note 7)
	Minimum Dynamic V <sub>OL</sub>						()( )
V <sub>IHD</sub>	Maximum High Level Dynamic Input Voltage	3.3	1.6	2.0		٧	(Note 6)(Note 8)
V <sub>ILD</sub>	Maximum Low Level Dynamic Input Voltage	3.3	1.6	0.8		٧	(Note 6)(Note 8)

 $\textbf{Note 3:} \ \textbf{All outputs loaded;} \ thresholds \ on \ input \ associated \ with \ output \ under \ test.$ 

 $\textbf{Note 4:} \ \textbf{Maximum test duration 2.0 ms, one output loaded at a time.}$ 

Note 5: Incident wave switching on transmission lines with impedances as low as  $75\Omega$  for commercial temperature range is guaranteed for.

Note 6: Worst case package.

Note 7: Max number of outputs defined as (n). Data inputs are driven 0V to 3.3V; one output at GND.

Note 8: Max number of Data Inputs (n) switching. (n - 1) inputs switching 0V to 3.3V. Input-under-test switching: 3.3V to threshold  $(V_{ILD})$ , 0V to threshold  $(V_{IHD})$ , f = 1 MHz.

## **AC Electrical Characteristics**

			$T_A = +25^{\circ}C$ $C_L = 50\;pF$			$T_A = -40$ °C to +85°C $C_L = 50$ pF		Units
Symbol	Parameter	v <sub>cc</sub>						
		(V)	Min	Тур	Max	Min	Max	
t <sub>PHL</sub>	Propagation Delay	2.7	2.5	10.2	14.8	2.5	16.0	no
t <sub>PLH</sub>	D <sub>n</sub> to O <sub>n</sub>	$3.3 \pm 0.3$	2.5	8.5	10.5	2.5	11.0	ns
t <sub>PLH</sub>	Propagation Delay	2.7	2.5	10.2	16.9	2.5	18.0	no
t <sub>PHL</sub>	LE to O <sub>n</sub>	$3.3 \pm 0.3$	2.5	8.5	12.0	2.5	12.5	ns
t <sub>PZL</sub>	Output Enable Time	2.7	2.5	10.2	18.3	2.5	19.0	no
$t_{PZH}$		$3.3 \pm 0.3$	2.5	8.5	13.0	2.5	13.5	ns
t <sub>PHZ</sub>	Output Disable Time	2.7	1.0	10.8	20.4	1.0	21.0	no
$t_{PLZ}$		$3.3 \pm 0.3$	1.0	9.0	14.5	1.0	15.0	ns
toshl	Output to Output Skew (Note 9)	2.7		1.0	1.5		1.5	ns
toslh	D <sub>n</sub> to O <sub>n</sub>	$3.3\pm0.3$		1.0	1.5		1.5	115

Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design.

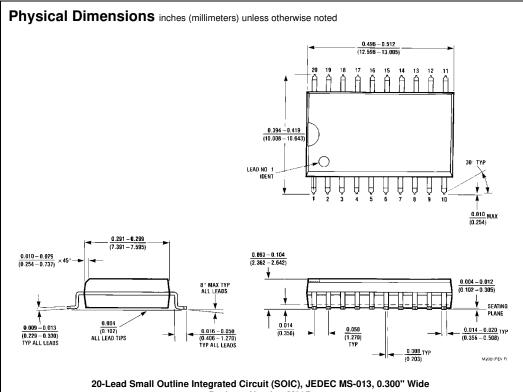
## **AC Operating Requirements**

Symbol	Parameter	v <sub>cc</sub>	T <sub>A</sub> = -	+25°C 50 pF	$T_A = -40$ °C to +85°C $C_L = 50$ pF	Units	
		(V)	Тур	Guaran	teed Minimum		
t <sub>S</sub>	Setup Time, HIGH or LOW	2.7	0	4.0	4.5	no	
	D <sub>n</sub> to LE	$3.3 \pm 0.3$	0	3.0	3.0	ns	
t <sub>H</sub>	Hold Time, HIGH or LOW	2.7	0	1.5	1.5	ns	
	D <sub>n</sub> to LE	$3.3 \pm 0.3$	0	1.5	1.5		
t <sub>W</sub>	LE Pulse Width, HIGH	2.7	2.4	5.0	6.0	20	
		$3.3\pm0.3$	2.0	4.0	4.0	ns	

## Capacitance

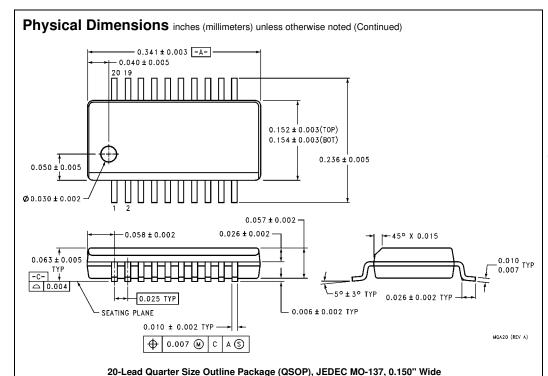
Symbol	Symbol Parameter		Units	Conditions	
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = Open	
C <sub>PD</sub> (Note 10)	Power Dissipation Capacitance	37	pF	V <sub>CC</sub> = 3.3V	

Note 10: C<sub>PD</sub> is measured at 10 MHz.



20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide Package Number M20B

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 2.6±0.10 0.40 TYP --A-5.01 TYP 5.3±0.10 9.27 TYP 7.8 -B-3.9 0.2 C B A ALL LEAD TIPS 10 PIN #1 IDENT.-0.6 TYP 1.27 TYP -LAND PATTERN RECOMMENDATION ALL LEAD TIPS SEE DETAIL A 0.1 C 2.1 MAX. 1.8±0.1 L 0.15±0.05 0.15-0.25 -1.27 TYP 0.35-0.51 **♦** 0.12 **⋈** C A DIMENSIONS ARE IN MILLIMETERS GAGE PLANE 0.25 NOTES: A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998. B. DIMENSIONS ARE IN MILLIMETERS. C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. 0.60±0.15 SEATING PLANE 1.25 -M20DRevB1 DETAIL A 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D



Package Number MQA20

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